

SODIFLUX

PRODUITS ET MATERIEL POUR L'ELECTRONIQUE

Sarl capital 10000 Euros RCS Pontoise 1980B00670-

APE 518L SIRET 309 662 757 00025



SUPER SWASH

Machine Automatique à Spray pour nettoyage des stencils et cartes électroniques

Good cleanliness of the stencils is a decisive parameter for good quality printing. Partially clogged apertures lead to serious printing errors, which diminish the quality of the assembly process. Growing demands on the print quality of e.g. BGA, QFP, CSP and other package types requires a very safe cleaning process, which is not dependent on the operator.

In the same time, it is adventurous to clean eventually misprint and PCB after soldering in the same equipment. **SUPER SWASH** is the machine which can do that!



SUPER SWASH - Flexible solution for high-tech cleaning

- Designed for use with non-inflammable cleaning agents, especially for **Micro-phase cleaners (MPC)**
 - Cleaning medium is efficiently regenerated inside the machine
 - The consumption of cleaning chemicals is drastically reduced due to innovative design of cleaning chamber and spray system
 - Exhaust port with PC control and fog absorber to minimize cleaner losses
 - Process can be easily monitored by means of frontal window and light wall
 - Programmable range of spraying, rinsing and drying field
 - Cleaning solution temperature up to 60°C
 - Drying temperature up to 110°C
 - Fully closed system with integrated DI water plant and contamination measuring in the basic configuration (excluding Super Swash I)
 - Ergonomic design for easy operation
 - Optionally a two- step rinsing for bigger capacity processes
 - Optionally - a pressure air tool for fast PUMP print stencil cleaning
 - Optionally - exhaust fan integrated to the system
- All parameters are controlled by PC with WINDOWS XP and touch screen interface
 - Fully programmable process with password protection and program library
 - Possibility of logging all process relevant parameters (full traceability process possible)

Machine can be built in following configurations:

SUPER SWASH I cleaning, tap water rinsing – to waste, drying

Process rating:	Stencil ☺☺☺	Pump print ☺☺☺	Misprint ☺	PCB low vol. ☺	PCB high.vol ☺☺☺	Solder pallet ☺☺☺	Flux traps ☺☺☺
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SUPER SWASH II cleaning, DI water rinsing, drying

Process rating:	Stencil ☺☺☺	Pump print ☺☺☺	Misprint ☺☺☺	PCB low vol. ☺☺☺	PCB high.vol ☺☺	Solder pallet ☺☺	Flux traps ☺☺☺
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SUPER SWASH III cleaning, tap water rinsing to waste, DI water rinsing, drying

Process rating:	Stencil ☺☺☺	Pump print ☺☺☺	Misprint ☺☺☺	PCB low vol ☺☺☺	PCB high.vol ☺☺☺	Solder pallet ☺☺☺	Flux traps ☺☺☺
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SUPER SWASH IV cleaning, DI water pre- rinsing, DI water rinsing, drying

Process rating:	Stencil ☺☺☺	Pump print ☺☺☺	Misprint ☺☺☺	DefluxPCB ☺☺☺	PCB high.vol ☺☺☺	Solder pallet ☺☺☺	Flux traps ☺☺☺
Capacity	6pcs/hr	2pcs/hr	3m2/hr	3m2/hr	3m2/hr	6cycle/hf	

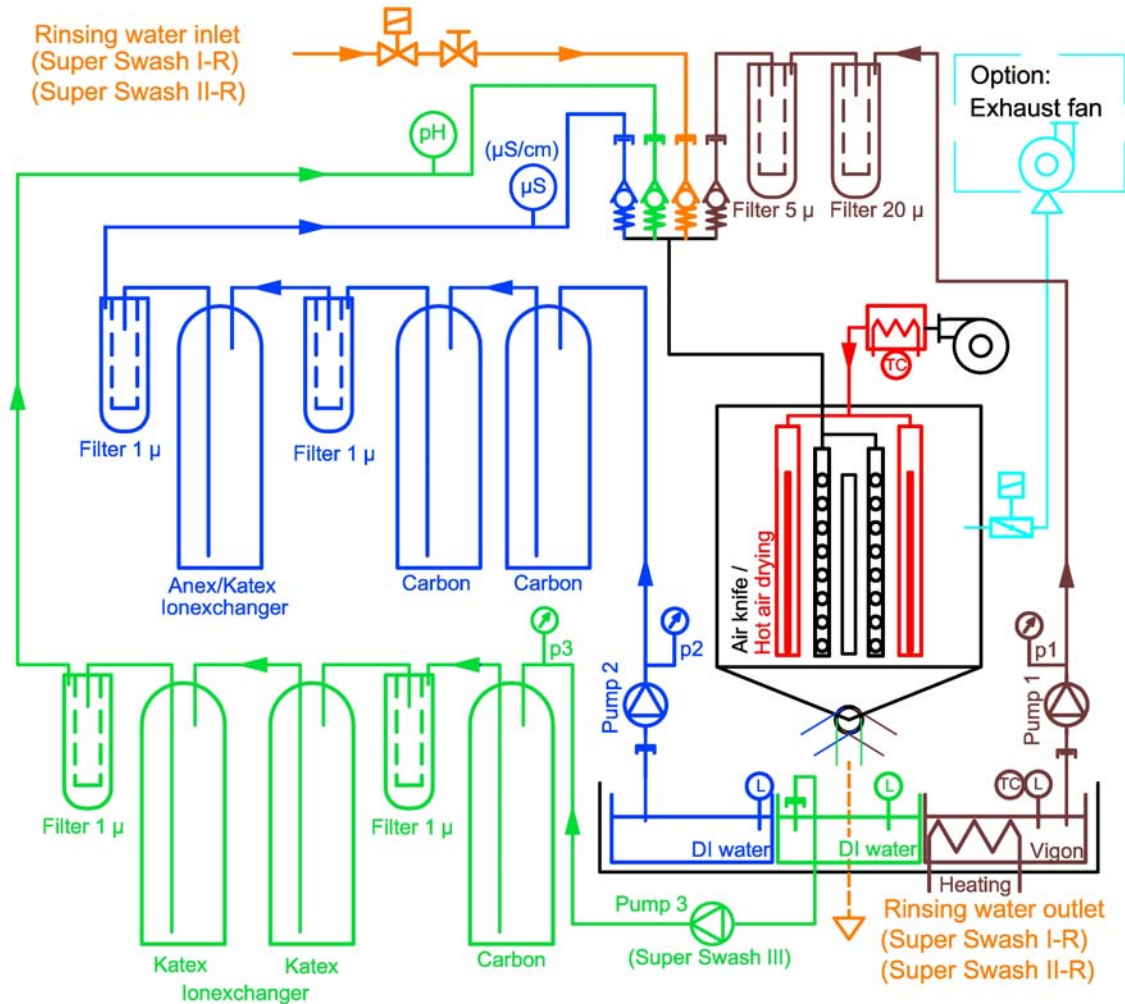
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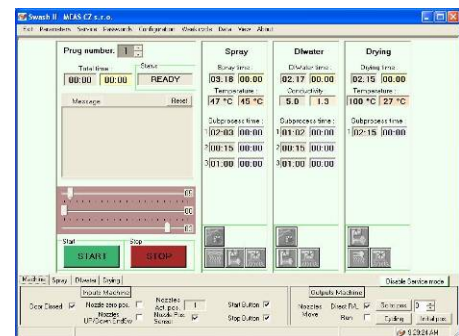
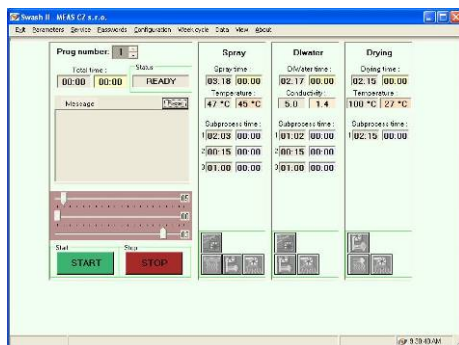
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Process diagram of SUPER SWASH system



Control system of SUPER SWASH

Machine operation and programming is very intuitive and does not need any special training. All programming and maintenance functions are protected by passwords



Special features of cleaning chamber

Compact configuration of spray and air/hot air nozzles provides very efficient and absolutely uniform cleaning and drying impact on the complete working area. Vertical orientation of nozzles and a very smooth inner face of the chamber minimize drag-out and cleaner consumption

The light wall helps to evaluate cleaning results.



Special option for pump-print stencil cleaning

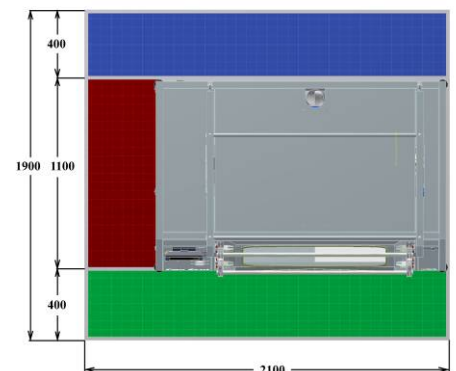
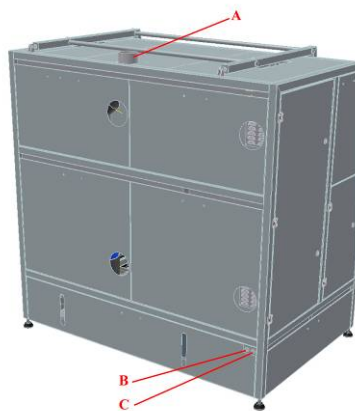
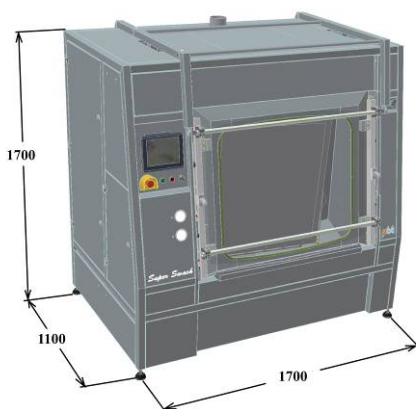
An air spray gun opens the apertures, filled with the glue. Thus the cleaning time for PUMP – Print stencils can be reduced for 50%



Technical data:

Maximum dimensions of cleaned object	750 x 830 x 75 mm
Typical cycle time	3-5 min/washing, 2 min/rinsing, 5-10 min drying
Cleaning liquid (VIGON SC200, VIGON SC202)	60 litres
Rinsing water	75 litres (each tank)
Compressed air supply (consumption)	0.50 MPa (50 l/min)
Installed power	SUPER SWASH I 12.5 kW
	SUPER SWASH II,.III 13.5 kW
	SUPER SWASH IV 14.5 kW
Power consumption during operation (average)	5 kW
Temperature of washing liquid	max 60°C
Max. temperature of hot air for drying	max. 110°C
Air supply for drying	high-pressure blower
Dimensions (L x W x H)	1700 x 1100 x 1700 mm
Weight (empty)	550 kg
Control system	industrial PC, WINDOWS XP®

Installation scheme



- A – exhaust port diam 100mm
- B –pressure air inlet
- C- cable connection position